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25V PNP LOW SATURATION TRANSISTOR IN SOT23

Features

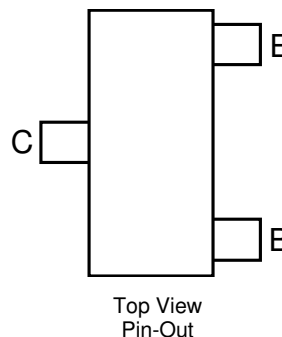
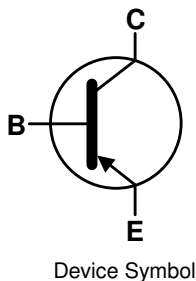
- $BV_{CEO} > -25V$
- $BV_{CEO} > -35V$ forward blocking voltage
- $I_C = -3A$ Continuous Collector Current
- Low Saturation Voltage, $V_{CE(SAT)} < -150mV @ -1A$.
- $R_{CE(sat)} = 87m\Omega$ for a low equivalent on-resistance
- 725mW power dissipation
- h_{FE} characterised up to -6A for high current hold-up
- Complementary NPN Type: ZXTN649F
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads
- Solderable per MIL-STD-202, Method 208③
- Weight 0.008 grams (Approximate)

Application

- MOSFET Gate Drivers
- Power Switching in Automotive and Industrial Applications
- Motor Drive and Control

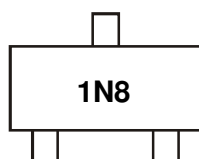


Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTP749FTA	1N8	7	8	3,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



1N8 = Product Type Marking Code

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-35	V
Collector-Emitter Voltage	V _{CEO}	-25	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current	I _C	-3	A
Peak Pulse Current	I _{CM}	-6	A
Base Current	I _B	-500	mA
Peak Pulse Current	I _{BM}	-2	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

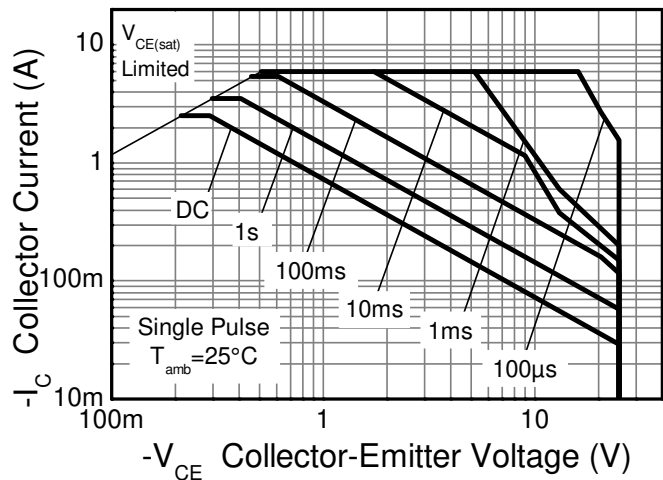
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	725	mW
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	172	°C/W
Thermal Resistance, Junction to Leads (Note 6)	R _{θJL}	79	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 7)

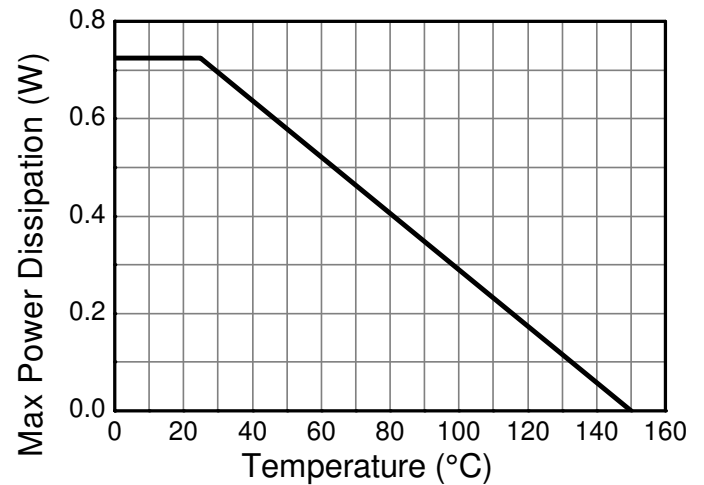
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
5. For a device surface mounted on 15mm x 15mm x 1.6mm FR4 PCB with high coverage of single sided 1 oz. copper, in still air conditions; the device is measured when operating in a steady-state condition.
 6. Thermal resistance from junction to solder-point (at the end of the collector lead).
 7. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

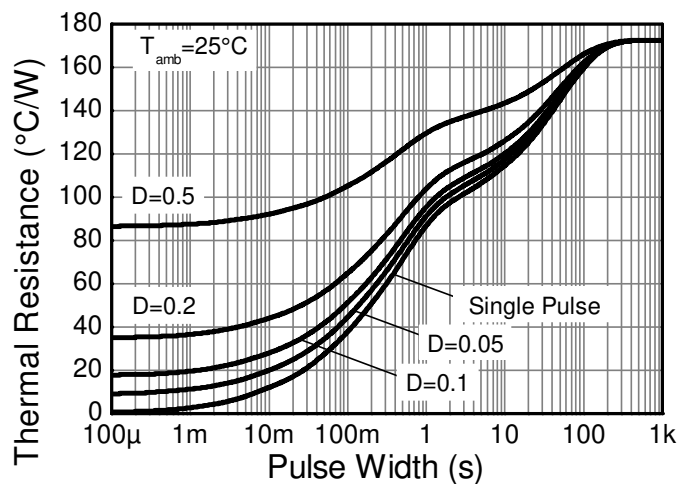
Thermal Characteristics and Derating information



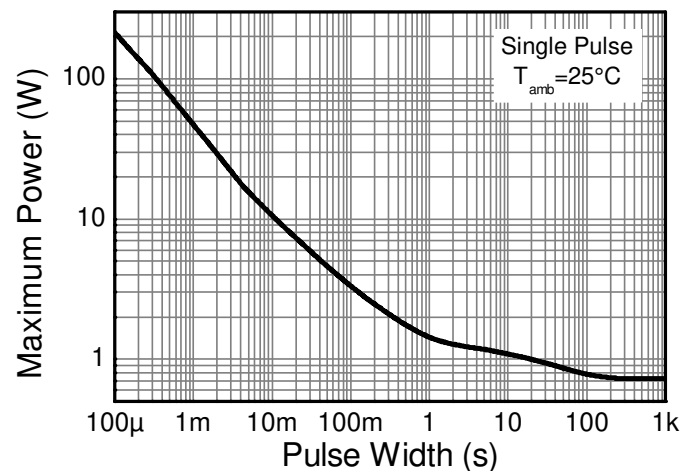
Safe Operating Area



Derating Curve



Transient Thermal Impedance



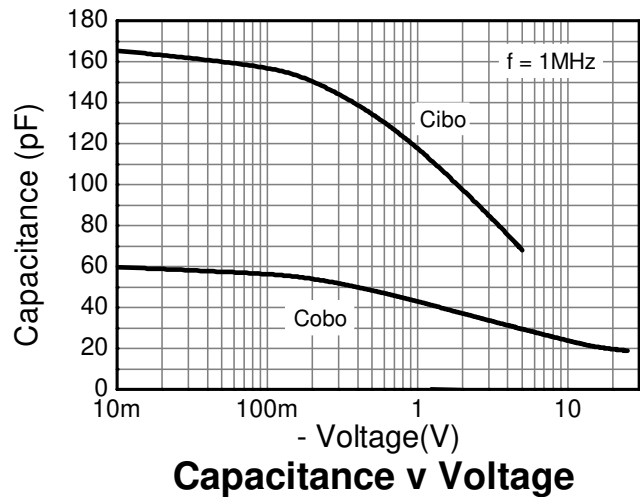
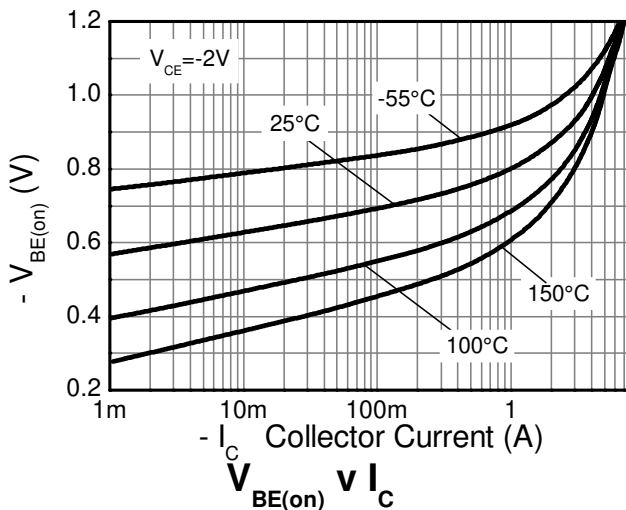
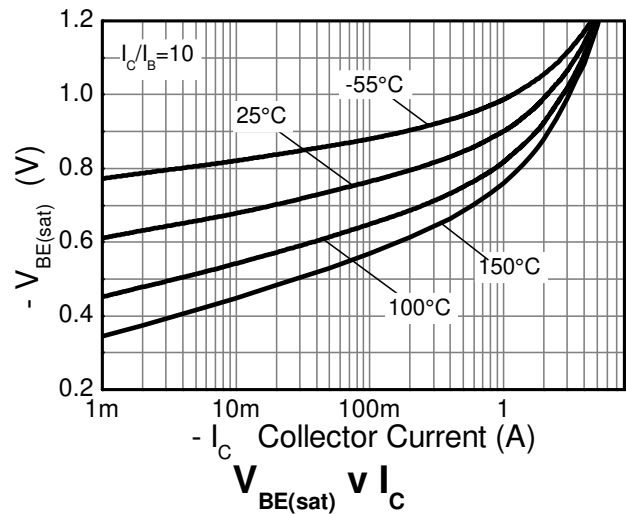
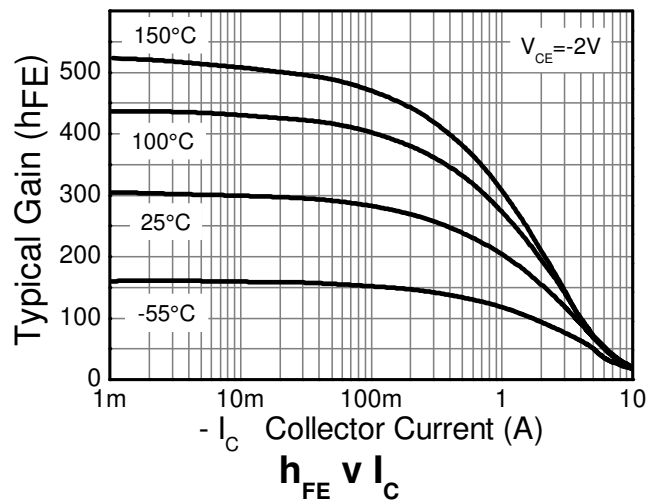
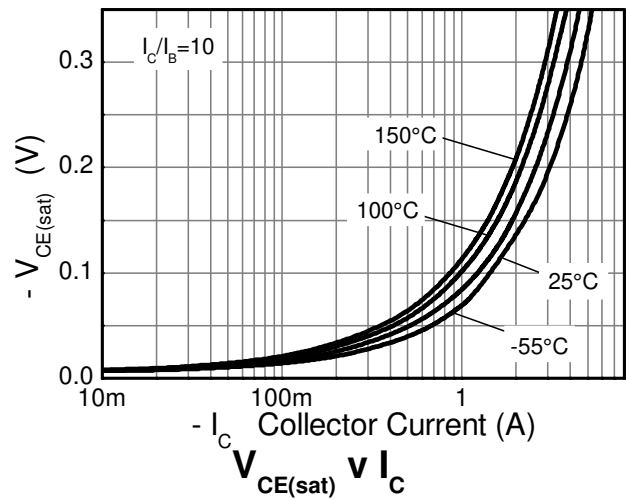
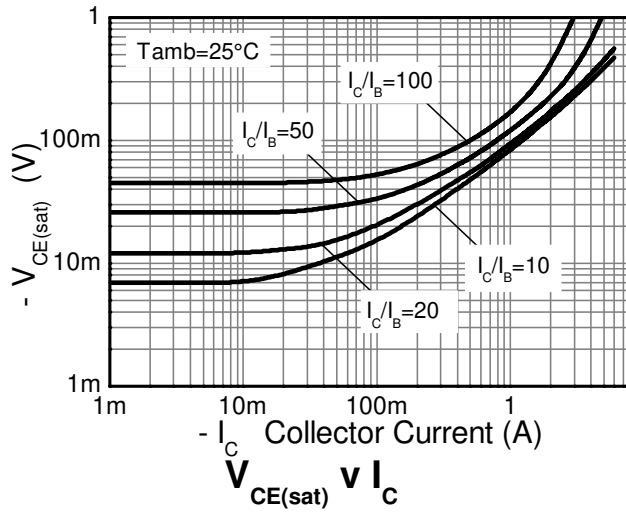
Pulse Power Dissipation

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-35	-60	-	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 8)	BV _{CEO}	-25	-40	-	V	I _C = -10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	-8.4	-	V	I _E = -100μA
Collector Cutoff Current	I _{CBO}	-	<1	-50 -0.5	nA μA	V _{CB} = -28V V _{CB} = -28V, T _A = +100°C
Emitter Cutoff Current	I _{EBO}	-	<1	-50	nA	V _{EB} = -5.6V
Static Forward Current Transfer Ratio (Note 8)	h _{FE}	200 130 100 25	320 230 180 50	500 - - -	-	I _C = -100mA, V _{CE} = -2V I _C = -1A, V _{CE} = -2V I _C = -2A, V _{CE} = -2V I _C = -6A, V _{CE} = -2V
Collector-Emitter Saturation Voltage (Note 8)	V _{CE(sat)}	- -	-85 -229	-150 -350	mV	I _C = -1A, I _B = -100mA I _C = -3A, I _B = -300mA
Base-Emitter Turn-On Voltage (Note 8)	V _{BE(on)}	-	-786	-850	mV	I _C = -1A, V _{CE} = -2V
Base-Emitter Saturation Voltage (Note 8)	V _{BE(sat)}	-	-895	-1,000	mV	I _C = -1A, I _B = -100mA

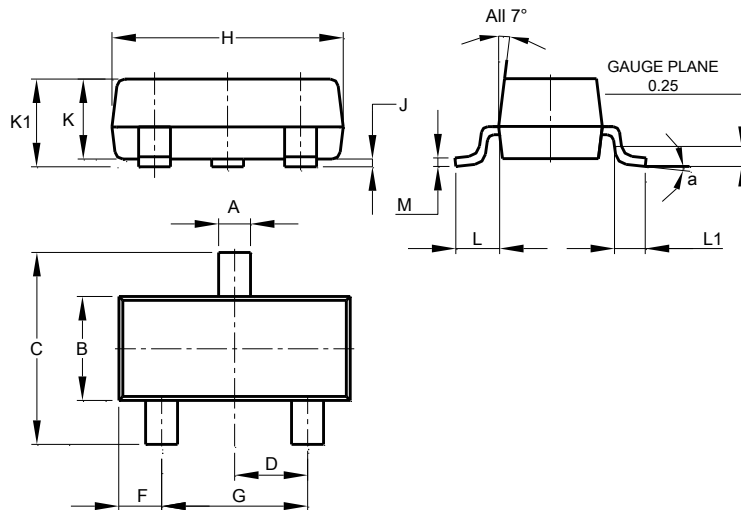
Notes: 8. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



Package Outline Dimensions

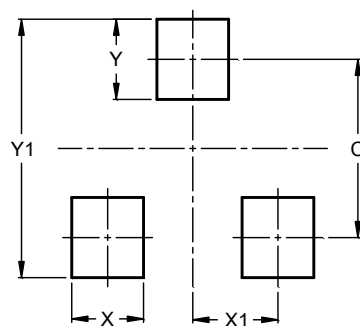
Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9

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